

Method for Improving the Mechanical Properties of BOC Module Arrangements

ABSTRACT OF THE DISCLOSURE

The invention relates to a method for improving the mechanical properties of BOC module arrangements in which chips have 3D structures, solder balls, μ springs or soft bumps which are mechanically and electrically connected by means of solder connections to terminal contacts on a printed circuit board or leadframe. Advantages are achieved by providing a casting compound for the wafer or the chips after they have been individually separated and before they are mounted on the printed circuit board in such a way that the tips of the 3D structures protrude from this compound. The casting compound preferably has elastic and mechanical properties comparable to those of silicon.